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Infineon Technologies BFY193 (P)

For any questions, you can email us directly: sales@integrated-circuit.com

Datasheet of BFY193 (P) - TRANS RF NPN 12V 80MA MICRO-X1

Contact us: sales@integrated-circuit.com Website: www.integrated-circuit.com



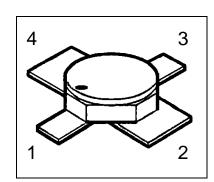
BFY193

HiRel NPN Silicon RF Transistor

- HiRel Discrete and Microwave Semiconductor
- For low noise, high-gain amplifiers up to 2GHz.
- For linear broadband amplifiers
- Hermetically sealed microwave package
- f_T= 8 GHz
 F = 2.3 dB at 2 GHz
- Space Qualified

ESA/SCC Detail Spec. No.: 5611/006

Type Variant No. 06



ESD: Electrostatic discharge sensitive device, observe handling precautions!

Туре	Marking	Ordering Code	Pin Configuration			Package	
			1	2	3 4		
BFY193 (ql)	-	see below	С	Е	В	Е	Micro-X1

(ql) Quality Level: P: Professional Quality

H: High Rel QualityS: Space Quality

ES: ESA Space Quality

(see order instructions for ordering example)

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BFY193

K/W

Symbol	Values	Unit
V _{CEO}	12	V
V _{CES}	20	V
V_{CBO}	20	V
V _{EBO}	2	V
I _C	80	mA
I _B	10 ¹⁾	mA
P _{tot}	580	mW
Tj	200	°C
T _{op}	-65+200	°C
T _{stg}	-65+200	°C
	V _{CEO} V _{CES} V _{CBO} V _{CBO} V _{EBO} I _C I _B P _{tot} T _j T _{op}	V _{CEO} 12 V _{CES} 20 V _{CBO} 20 V _{EBO} 2 I _C 80 I _B 10 ¹⁾ P _{tot} 580 T _j 200 T _{op} -65+200

 $R_{\text{th JS}}$

< 165

Notes.:

- 1) The maximum permissible base current for V_{FBE} measurements is 30mA (spot-measurement duration < 1s)
- 2) At T_S = + 104 °C. For T_S > + 104 °C derating is required.
- 3) T_S is measured on the collector lead at the soldering point to the pcb.

Electrical Characteristics

Junction-soldering point 3)

at T_A=25°C; unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-base cutoff current	I _{CBO}	-	-	100	μΑ
$V_{CB} = 20 \text{ V}, I_{E} = 0$					
Collector-emitter cutoff current	I _{CEX}	-	-	600	μA
$V_{CE} = 12 \text{ V}, I_B = 0.5 \mu A$ 1.)					
Collector-base cutoff current	I _{CBO}	-	-	50	nA
$V_{CB} = 10 \text{ V}, I_{E} = 0$					
Emitter base cuttoff current	I _{EBO}	-	-	25	μΑ
$V_{EB} = 2 \text{ V}, I_{C} = 0$					
Emitter base cuttoff current	I _{EBO}	-	-	0.5	μΑ
$V_{EB} = 1 \text{ V}, I_C = 0$					
NI . 4					

Notes:

1.) This Test assures V(BR)CE0 > 12V

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Electrical Characteristics (continued)

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics			•		
Base-Emitter forward voltage	V_{FBE}	-	-	1	V
$I_E = 30 \text{ mA}, I_C = 0$					
DC current gain	h _{FE}	50	100	175	-
$I_C = 30$ mA, $V_{CE} = 8$ V					
AC Characteristics					
Transition frequency	f _T				GHz
$I_C = 40 \text{mA}, \ V_{CE} = 5 \ V, \ f = 500 \ MHz$		6,5	7.5	-	
I_C = 50 mA, V_{CE} = 8 V, f = 500 MHz		-	8	-	
Collector-base capacitance	C _{CB}	-	0.56	0.75	pF
$V_{CB} = 10 \text{ V}, V_{BE} = \text{vbe} = 0, f = 1 \text{ MHz}$					
Collector-emitter capacitance	C _{CE}	-	0.34	-	pF
$V_{CE} = 10 \text{ V}, V_{BE} = \text{vbe} = 0, f = 1 \text{ MHz}$					
Emitter-base capacitance	C _{EB}	-	1.9	2.4	pF
$V_{EB} = 0.5V$, $V_{CB} = vcb = 0$, $f = 1 MHz$					
Noise Figure	F	-	2.3	2.9	dB
$I_C = 15 \text{ mA}, V_{CE} = 5 \text{ V}, f = 2 \text{ GHz},$					
$Z_S = Z_{Sopt}$					
Power gain	Gma 1.)	12.5	13.5	-	dB
$I_C = 40$ mA, $V_{CE} = 5V$, $f = 2$ GHz					
$Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$					
Transducer gain	$\left S_{21e}\right ^2$	8	9	-	dB
$I_C = 40$ mA, $V_{CE} = 5$ V, $f = 2$ GHz					
$Z_S = Z_L = 50 \Omega$					
Output Power	P _{OUT}	16.5	17.5	-	dBm
$I_C = 50$ mA, $V_{CE} = 5$ V, $f = 2GHz$,					
P_{IN} =10dBm, $Z_S = Z_L = 50 \Omega$					

Notes.:

1.)
$$G_{ma} = \left| \frac{S21}{S12} \right| (k - \sqrt{k^2 - 1}), \quad G_{ms} = \left| \frac{S21}{S12} \right|$$

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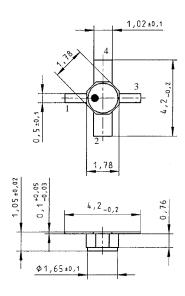
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BFY193

Micro-X1 Package



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